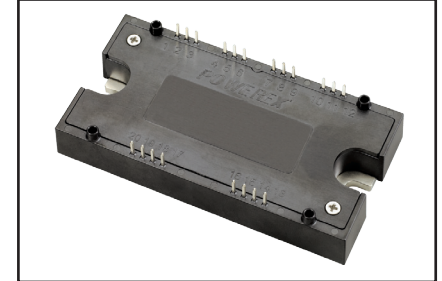
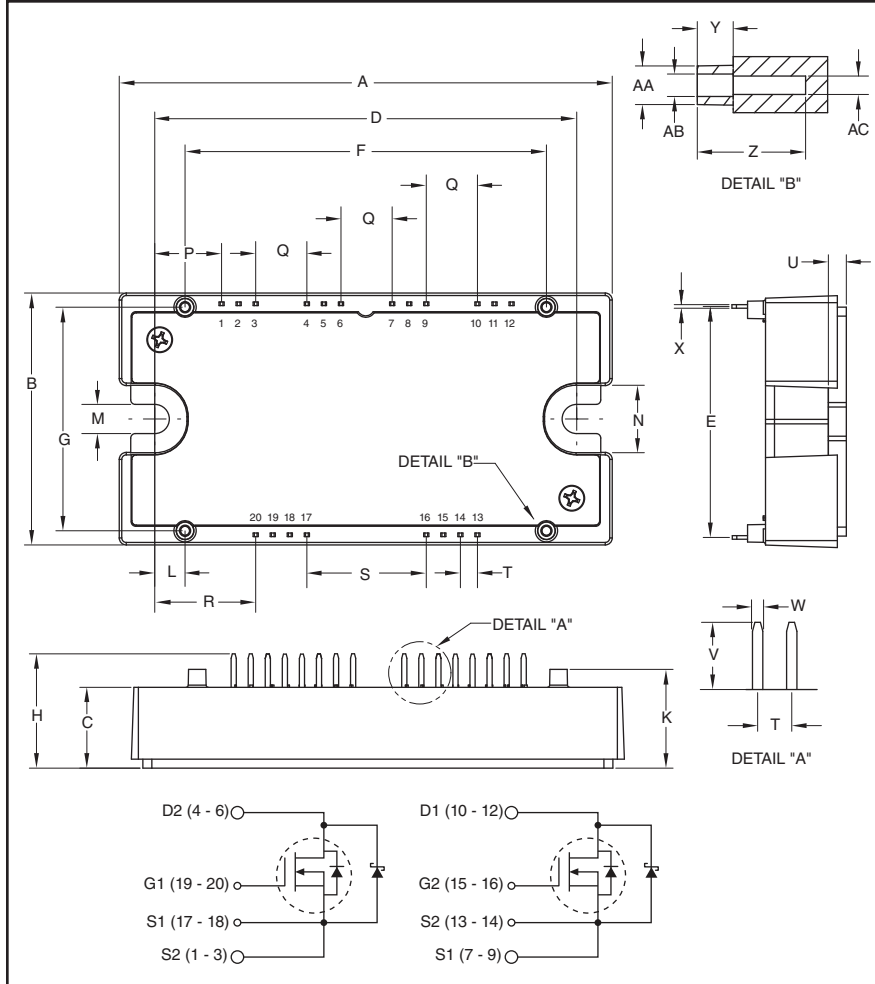


Split Dual SiC MOSFET Module 100 Amperes/1200 Volts



Description:

Powerex Silicon Carbide MOSFET Modules are designed for use in high frequency applications. Each module consists of two MOSFET Silicon Carbide Transistors with each transistor having a reverse connected fast recovery free-wheel silicon carbide Schottky diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- Junction Temperature: 175°C
- Silicon Carbide Chips
- Low Internal Inductance
- Industry Leading RDS(on)
- High Speed Switching
- Low Switching Losses
- Low Capacitance
- Low Drive Requirement
- Fast 100A Free Wheeling Schottky Diode
- High Power Density
- Isolated Baseplate
- Aluminum Nitride Isolation
- 2 Individual Switches per Module
- AlSiC Baseplate

Applications:

- Energy Saving Power Systems such as:
Fans; Pumps; Consumer Appliances
- High Frequency Type Power Systems such as:
UPS; High Speed Motor Drives; Induction Heating; Welder; Robotics
- High Temperature Power Systems such as:
Power Electronics in Electric Vehicle and Aviation Systems

Outline Drawing and Circuit Diagram

| Dimensions | Inches | Millimeters |
|------------|-----------|-------------|
| A | 4.32 | 109.8 |
| B | 2.21 | 56.1 |
| C | 0.71 | 18.0 |
| D | 3.70±0.02 | 94.0±0.5 |
| E | 2.026 | 51.46 |
| F | 3.17 | 80.5 |
| G | 1.96 | 49.8 |
| H | 1.00 | 25.5 |
| K | 0.87 | 22.0 |
| L | 0.266 | 6.75 |
| M | 0.26 | 6.5 |
| N | 0.59 | 15.0 |
| P | 0.586 | 14.89 |

| Dimensions | Inches | Millimeters |
|------------|-----------|-------------|
| Q | 0.449 | 11.40 |
| R | 0.885 | 22.49 |
| S | 1.047 | 26.6 |
| T | 0.15 | 3.80 |
| U | 0.16 | 4.0 |
| V | 0.30 | 7.5 |
| W | 0.045 | 1.15 |
| X | 0.03 | 0.8 |
| Y | 0.16 | 4.0 |
| Z | 0.47 | 12.1 |
| AA | 0.17 Dia. | 4.3 Dia. |
| AB | 0.10 Dia. | 2.5 Dia. |
| AC | 0.08 Dia. | 2.1 Dia. |

QJD1210011
Split Dual SiC MOSFET Module
 100 Amperes/1200 Volts

Absolute Maximum Ratings, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

| Ratings | Symbol | QJD1210011 | Units |
|--|-----------------------|------------|------------------|
| Drain-Source Voltage (G-S Short) | V_{DSS} | 1200 | Volts |
| Gate-Source Voltage | V_{GSS} | -5 / +25 | Volts |
| Drain Current (Continuous) at $T_C = 150^\circ\text{C}$ | I_D | 100 | Amperes |
| Drain Current (Pulsed)* | $I_{D(\text{pulse})}$ | 250 | Amperes |
| Maximum Power Dissipation ($T_C = 25^\circ\text{C}$, $T_j < 175^\circ\text{C}$) | P_D | 900 | Watts |
| Junction Temperature | T_j | -40 to 175 | $^\circ\text{C}$ |
| Storage Temperature | T_{stg} | -40 to 150 | $^\circ\text{C}$ |
| Mounting Torque, M6 Mounting Screws | — | 40 | in-lb |
| Module Weight (Typical) | — | 140 | Grams |
| V Isolation Voltage | V_{RMS} | 3000 | Volts |

MOSFET Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

| Characteristics | Symbol | Test Conditions | Min. | Typ. | Max. | Units |
|-----------------------------------|---------------------|---|------|------|------|------------------|
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $I_D = 50\mu\text{A}$, $V_{GS} = 0$ | 1200 | — | — | Volts |
| Zero Gate Voltage Drain Current** | I_{DSS} | $V_{GS} = 0$, $V_{DS} = 1200\text{V}$ | — | 0.35 | 2.6 | mA |
| Zero Gate Voltage Drain Current** | I_{DSS} | $V_{GS} = 0$, $V_{DS} = 1200\text{V}$, $T_j = 175^\circ\text{C}$ | — | 0.40 | 4.0 | mA |
| Gate Leakage Current | I_{GSS} | $V_{DS} = 0$, $V_{GS} = 20\text{V}$ | — | — | 1.5 | μA |
| Gate Threshold Voltage | $V_{GS(\text{th})}$ | $V_{DS} = V_{GS}$, $I_D = 10\text{mA}$ | 1.5 | 2.5 | 5.0 | Volts |
| | | $V_{DS} = V_{GS}$, $I_D = 10\text{mA}$, $T_j = 175^\circ\text{C}$ | 1.0 | 1.7 | 5.0 | Volts |
| Drain-Source On Resistance | $R_{DS(\text{on})}$ | $I_D = 100\text{A}$, $V_{GS} = 20\text{V}$ | — | 15 | 25 | $\text{m}\Omega$ |
| | | $I_D = 100\text{A}$, $V_{GS} = 20\text{V}$, $T_j = 175^\circ\text{C}$ | — | 20 | 32 | $\text{m}\Omega$ |
| Gate to Source Charge | Q_{gs} | $V_{DD} = 800\text{V}$, $I_D = 100\text{A}$ | — | 140 | — | nC |
| Gate to Drain Charge | Q_{gd} | $V_{DD} = 800\text{V}$, $I_D = 100\text{A}$ | — | 220 | — | nC |
| Total Gate Charge | Q_G | $V_{CC} = 800\text{V}$, $I_C = 100\text{A}$, $V_{GS} = -5/20\text{V}$ | — | 500 | — | nC |
| Body Diode Forward Voltage | V_{SD} | $I_F = 50\text{A}$, $V_{GS} = -5\text{V}$ | — | 4.0 | — | Volts |
| Input Capacitance | C_{iss} | | — | 10.2 | — | nF |
| Output Capacitance | C_{oss} | $V_{GS} = 0$, $V_{DS} = 800\text{V}$, $f = 1\text{MHz}$ | — | 1.0 | — | nF |
| Reverse Transfer Capacitance | C_{rss} | | — | 0.1 | — | nF |
| Turn-on Delay Time | $t_{d(\text{on})}$ | $V_{DD} = 800\text{V}$, $I_D = 100\text{A}$, | — | 17.2 | — | ns |
| Rise Time | t_r | $V_{GS} = -2/20\text{V}$, | — | 13.6 | — | ns |
| Turn-off Delay Time | $t_{d(\text{off})}$ | $R_G = 6.8\Omega$ | — | 62 | — | ns |
| Fall Time | t_f | Inductive Load | — | 35.6 | — | ns |

* Pulse width and repetition rate should be such that device junction temperature (T_j) does not exceed $T_{j(\text{max})}$ rating.

**Total module leakage includes MOSFET leakage plus reverse Schottky diode leakage.

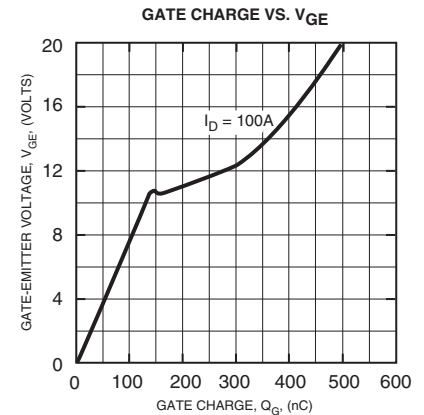
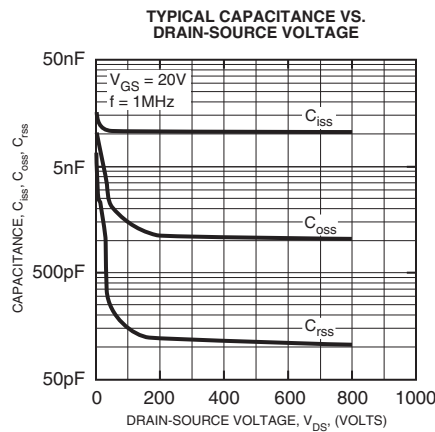
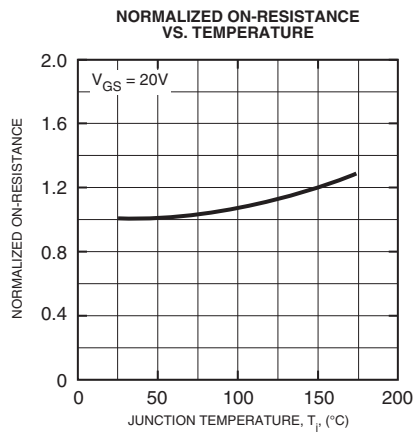
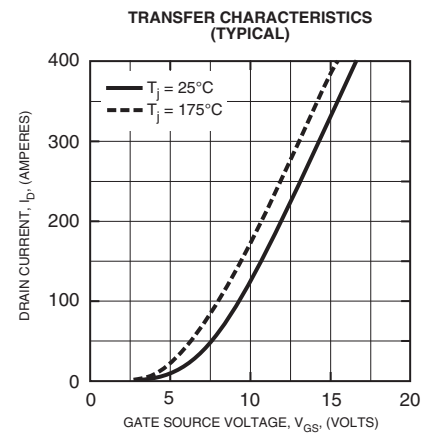
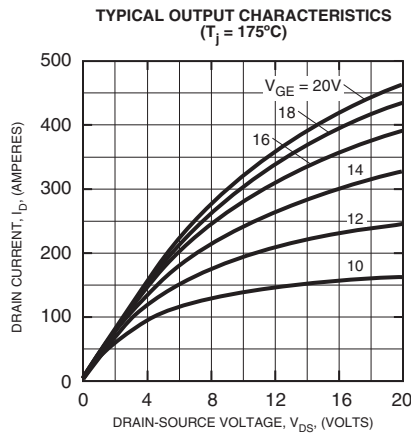
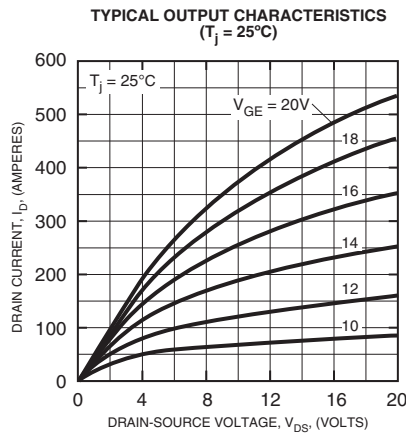
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Reverse Schottky Diode Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

| Characteristics | Symbol | Test Conditions | Min. | Typ. | Max. | Units |
|-------------------------|----------|---|------|------|------|-------|
| Diode Forward Voltage | V_{FM} | $I_F = 100\text{A}, V_{GS} = -5\text{V}$ | — | 1.6 | 2.0 | Volts |
| | | $I_F = 100\text{A}, V_{GS} = -5\text{V}, T_j = 175^\circ\text{C}$ | — | 2.5 | 3.2 | Volts |
| Diode Capacitive Charge | Q_C | $V_R = 1200\text{V}, I_F = 100\text{A}, di/dt = 4000\text{A}/\mu\text{s}$ | — | 550 | — | nC |

Thermal and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

| Characteristics | Symbol | Test Conditions | Min. | Typ. | Max. | Units |
|--------------------------------------|---------------|--|------|------|-------|---------------------------|
| Thermal Resistance, Junction-to-Case | $R_{th(j-c)}$ | MOSFET Part | — | — | 0.167 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Case | $R_{th(j-c)}$ | Diode Part | — | — | 0.294 | $^\circ\text{C}/\text{W}$ |
| Contact Thermal Resistance | $R_{th(c-s)}$ | Per 1/2 Module, Thermal Grease Applied | — | 0.04 | — | $^\circ\text{C}/\text{W}$ |
| Internal Inductance | L_{int} | MOSFET Part | — | 10 | — | nH |



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